



IEEE 2024 INTERNATIONAL 3D SYSTEMS  
INTEGRATION CONFERENCE  
September 25-27, 2024 Sendai, Japan  
September 25 at Hotel Metropolitan Sendai  
September 26-27 at Sendai Kokusai Hotel



## KEYNOTE TALK V

**08:50-09:20, September 27**

**TBA**

**Dr. Robert Patti**

*CEO*

*NHanced Semiconductors*



### **Abstract:**

### **CV:**

Bob Patti is the owner, President, and CEO of NHanced Semiconductors, a spin-out of Tezzaron Semiconductors. Bob established NHanced to further advance and develop 2.5D/3D technologies, chiplets, die and wafer stacking, and other advanced packaging.

Prior to starting NHanced, Bob served as CTO of Tezzaron Semiconductor Corporation, a leading force in 3D integrated circuit (3DIC) technology that built its first working 3DIC in 2004. Tezzaron grew out of Bob's initial startup, ASIC Designs Inc., an R&D company specializing in high-performance systems and ASICs. During his 12 years with ASIC Designs he helped design over 100 chips.

Bob received the SEMI Award for North America in 2009, served as Vice-Chairman of JEDEC's DDRIII / Future Memories Task Group, and holds 21 US patents, numerous foreign patents, and many more pending patent applications in deep sub-micron semiconductor technologies. He holds a BSEE/CS and BSPH from Rose-Hulman Institute of Technology.